



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Group Art Unit: 1732

**Brian W. Baird, Michael J. Wolfe,
Richard S. Harris, Kevin P. Fahey,
Lian-Cheng Zou, and Thomas R. McNeil**

Application No. 10/017,497

Filed: December 14, 2001

For: **ULTRAVIOLET LASER ABLATIVE PATTERNING
OF MICROSTRUCTURES IN SEMICONDUCTORS**

Examiner:

Date: October 18, 2002

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INFORMATION DISCLOSURE STATEMENT

TO THE COMMISSIONER FOR PATENTS:

Pursuant to their duty of disclosure, applicants enclose copies of the documents listed on the accompanying Form PTO-1449.

1. This information disclosure statement is being submitted:

- a. Within three months of the filing date of the above-identified application or within three months of the date of entry of the national stage, or before the mailing date of the first Office action on the merits, whichever event occurs last. (No statement under 37 CFR 1.97(e) is required.)
- b. After the period set forth in paragraph 1a, but before the mailing date of either a final action or a notice of allowance. (Check box i. or ii.)
 - i. A \$240.00 information disclosure statement submission fee set forth in 37 CFR 1.17(p) is enclosed.
 - ii. A statement specified by 37 CFR 1.97(e) is set forth below.
- c. After the mailing date of a final action or notice of allowance and on or before payment of an issue fee. A statement specified by 37 CFR 1.97(e) is set forth below. A petition requesting consideration of the information

disclosure statement and the \$130.00 petition fee set forth in 37 CFR 1.17(i) are enclosed.

2. The attorney or agent signing below hereby states that:

- each item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement.
- no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the statement after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the information disclosure statement.

3. Applicant(s) set forth below concise explanations of the relevance of each document not in the English language and/or selected document(s) in the English language.

Respectfully submitted,

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Richard S. Harris, Kevin P. Fahey,
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By:



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FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
50001/83:2 USAAPPLICATION NO.
10/017,497INFORMATION DISCLOSURE CITATION
(Uses several sheets if necessary)APPLICANTS
Baird et al.FILING DATE
December 14, 2001GROUP
1732

U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	CA	6,423,925 B1	07/23/2002	Sukhman et al.	219	121.6	02/17/2000
	CB	6,420,245 B1	07/16/2002	Manor	438	460	04/30/2001
	CC	6,069,769	05/30/2000	Dorius et al.	360	103	
	CD	6,060,684	05/09/2000	Moriike	219	121.72	
	CE	5,987,725	11/23/1999	Church et al.	29	407.05	
	CF	5,589,090	12/31/1996	Song	219	121.62	
	CG	5,166,493	11/24/1992	Inagawa et al.	219	121.71	
	CH	4,835,361	05/30/1989	Strom	219	121.85	
	CI	4,169,976	10/02/1979	Cirri	219	121 LM	
	CJ						
	CK						

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	CL							
	CM							

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

↗	CN	"Creation of an Air Bearing Surface by Excimer Laser Patterning of Ceramic," IBM Technical Disclosure Bulletin, September 1991, US, Vol. 34, Issue No. 4B, pp. 59-60; published September 1, 1991, TDB-ACC-NO: NB910959.
↖	CO	"Method of Preventing Damage to Integrated Circuit Chips during Wafer Dicing," IBM Technical Disclosure Bulletin, May 1992, US, Vol. 34, Issue No. 12, pp. 311-312, published May 1, 1992, TDB-ACC-NO: NN9205311.
←	CP	Search Report concerning corresponding International Application No. PCT/US02/00867.

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.